

製造科技 MANUFACTURING TECHNOLOGY

新加坡微型傳感器及零部件 – 生產技術及應用海外培訓課程 Overseas Training Course to Singapore on Advanced Micro-Sensor and Components Manufacturing and Application Technologies 23-27 March 2015

好消息!
本課程已獲職業訓練局
新科技培訓計劃(NTTS)
預先批核

傳感器是許多高附加值產品的重要組成部分。隨着市場對微型化和高附加值的電子、電器、汽車和醫療設備的需求不斷增長，微型傳感器市場亦隨之迅速增長。基於微機電系統 (MEMS) 技術，高精度微型傳感器的發展趨向多元化，其優勝之處包括：增加新的功能或提高性能，降低成本、重量和體積。大部分香港及珠三角地區的製造商開始將不同類型的 MEMS 傳感器和零部件用於其高附加值的產品。然而，他們在裝嵌各種傳感器到產品設計時，一直面對著設計靈活性的挑戰。因此，本地廠商必須更深入地了解 MEMS 傳感器的技術、製造及測試所需的技術及設施，以更有效地運用這些傳感器組件，從而降低產品生產成本，並利用各種潛在的新型傳感器，擴大產品的應用範圍。最近，亞洲不少國家如新加坡已成功建立一個完善的 MEMS 供應鏈，提供從設計到原型小批量生產的代工服務。此外，新加坡許多科學研究所和研發代工廠擁有先進的生產設備和研發設施，開發基於 MEMS 和納米技術的新型傳感器及設備。

Sensors act as critical components of many high-value products. With the growing demand of the miniaturized and high-value added electronic, electrical, automotive and medical devices, the market of micro-sensors has been increased rapidly in recent years. Based on the MicroElectroMechanical Systems (MEMS) technology, a diverse range of high-precision micro-sensors can be developed with attractive benefits including the ability to add features or enhance performance at lower cost, weight and size. Most of the manufacturers in Hong Kong and Pearl Delta Region started adopting different types of MEMS sensors and components in their high-value added products. However, they have been suffering from challenges in design flexibility when integrating various sensors into their own product designs. Therefore, it is necessary for local manufacturers to establish ways of acquiring the relevant MEMS technology so as to reduce the costs of productions and to exploit various opportunities to expand the potential product ranges.

With the support from the Singapore government, a sustainable MEMS supply chain, from design to prototyping, has been built up in Singapore. Research institutes and R&D foundry have been established in Singapore with excellent research infrastructure for developing many novel sensor devices based on MEMS and nanotechnology.

傳感器的主要應用 MEMS Applications

- 應用於汽車內的安全氣囊和輪胎壓力傳感器
Airbags and tire pressure sensors in cars
- 智能手機的加速度計和陀螺儀
Accelerometers and gyroscope in smart phones
- 應用於生物醫學的遙距監控設備
Remote monitoring devices for biomedical application
- 汽車影像系統 Imaging system for automobile
- 監控環境和食品安全的生物傳感器芯片
Bio-sensors for environmental and food safety monitoring
- 應用於快速診斷的生物傳感器芯片
Bio-sensor chips for medical diagnosis

課程目的 Aims

本培訓課程旨在獲取最新的 MEMS 傳感器技術，讓參加者深入了解 MEMS 傳感器/設備的設計和製造原則和要求、關鍵生產和檢測技術、MEMS 傳感器的整合、新興 MEMS 傳感器零部件在不同高附加值產品的應用。

The training course aims at acquiring latest MEMS sensor technology in Singapore and providing an in-depth understanding in the topics in the MEMS sensor/device design and fabrication principles and requirement, critical manufacturing, testing technologies and integration of MEMS sensor products and the emerging applications of MEMS sensors and components.

課程對象 Target Participants

歡迎從事各行業人士 (如醫療及保健設備、汽車零部件、電子、電器、消費類產品、樓宇及建造等) 參加，其中包括：管理人員、專業人士、技術主任、工程師、技術顧問、產品設計經理、研發人員及技師等。

Management executives, professionals, technical officers, engineers, technologists, product development managers, R&D and technicians, from the micro-sensor related industries, such as medical and healthcare device, automotive parts, electronic, electrical and 3C products, building and construction, and etc.

成功完成課程者將獲新加坡理工學院發出的培訓證書乙張 Each participant will be awarded a Training Certificate upon the completion of the course, which is issued by Singapore Polytechnic.

新科技培訓計劃 New Technology Training Scheme (NTTS)

本課程已獲職業訓練局新科技培訓計劃(NTTS)預先批核。每位合資格參加者可申請培訓津貼最高為 50% 實際課程費用 (不多於港幣 6,375 元) 名額 20 人。This is a pre-approved training course under the NTTS. The maximum number of trainees is 20 and the approved training grant for each eligible trainee is 50% of the actual course fee up to HK\$6,375.

培訓課 + 實踐課 + 企業分享
參觀 MEMS 代工廠、新加坡 A*STAR
科技研究所，與微電子、微流體、表面
技術專家會面

Lecture + Practical sessions + Cases
sharing on the industrial application of
MEMS sensors

Visit to Singapore MEMS sensor
foundries, A*STAR research institutes
and meet with experts in
microelectronics, microfluidics and
surface technology group

參觀生產流程包括:

- 薄膜濺積技術 (Thin-film deposition)
- 光刻和納米圖案化
(Photolithography and nano-patterning)
- 蝕刻技術
(Wet and dry etching techniques)
- 表面微加工 (micromachining)
- 深矽微加工
(deep silicon micromachining)
- 聚焦離子束研磨
(focus ion beam milling)
- 微成型 (micro-molding)
- 納米壓印 (nano-imprinting)

主辦機構
Organizer :



協辦機構
Co-organizer :



支持機構
Supporting Organizations :



製造科技 MANUFACTURING TECHNOLOGY

日期 Date	行程 (Programme)
3月23日(一) 23 Mar (MON)	由香港出發到新加坡 Depart from Hong Kong to Singapore
3月24日(二) 【共7個小時】 24 Mar (TUE)	培訓 - 單元一及二：概論(微機電系統、集成電路及設計原理)·微/納米製造和生產流程 單元三：MEMS 傳感器/器件的封裝、可靠性測試和認證 Module I-II: Introduction to MEMS, Integrated Circuits & Design Principles, Micro/Nano Fabrication & Manufacturing Flow Module III: Packaging, Reliability Testing and Qualification of MEMS sensors/devices
(Total training hours: 7 hours)	
3月25日(三) 【共7個小時】 25 Mar (WED)	培訓 - 單元四：實例分析(微型機械傳感器、微光機電系統) 單元五：實踐課(微機電系統 MEMS 製程) Module IV: Case Studies (Mechanical micro-sensors, MOEMS) Module V: Practical sessions on MEMS processes
(Total training hours: 7 hours)	
3月26日(四) 【共7個小時】 26 Mar (THU)	培訓 - 單元四：實例分析(生物微機電系統 - 概論及應用) 單元五：實踐課(微機電系統 MEMS 製程) Module IV: Case Studies (BIOMEMS-Basics and applications) Module V: Practical sessions on MEMS processes
(Total training hours: 7 hours)	
3月27日(五) 27 Mar (FRI)	參觀 MEMS 代工廠、新加坡 A*STAR(Agency for Science, Technology and Research)科技研究所 Visit to MEMS foundries and A*STAR research institutes 離開新加坡 Depart from Singapore to Hong Kong

本局保留更改培訓內容、地點及時間的權利。

Note: HKPC reserves the right to change the contents, venue and / or time as necessary.

課程大綱 Training Content

單元一：概論(微機電系統、集成電路及設計原理)

Module I: Introduction to MEMS, Integrated Circuits & Design Principles

- * 概述 MEMS 與集成電路
- * 瞭解 MEMS 在日常生活的應用，特別是消費電子產品中的 MEMS 傳感器及零部件的設計及運作原理
- * 具體的案例研究說明微機電系統的應用範圍
- * 微型旋轉陀螺：設計方法及原理，製造工藝簡要說明，性能和可靠性評估，以及商品化的要求及過程。
- * General introduction to MEMS & Integrated Circuits
- * Relevance to everyday life with emphasis in Consumer Electronics market
- * Specific case study to illustrate scope of MEMS
- * Micro-rotating gyroscope: design considerations and principle, brief description of fabrication processes for this device, packaging, assessment of performance and reliability, and road to commercialization

單元二：微/納米製造和生產流程

Module II: Micro/Nano Fabrication & Manufacturing Flow

- * 介紹 MEMS 傳感器及零部件的基本製造工藝
- * 瞭解各個 MEMS 製造過程：如薄膜澱積技術，光刻和納米圖案化，蝕刻技術，表面微加工，體微機械加工，深矽微加工，納米加工，聚焦離子束研磨，微成型，納米壓印，晶圓鍵合，晶圓級封裝等。
- * Introduction to basic MEMS micro and nano fabrication processes flow
- * Participants would be introduced to the various MEMS fabrication processes; Thin-film deposition techniques, Photolithography and nano-patterning, Wet and dry etching techniques, surface micromachining, bulk micromachining, deep silicon micromachining, nano-machining, focus ion beam milling, micro-molding, nano-imprinting, nano-embossing, wafer bonding, wafer-level packaging

主辦機構
Organizer :



協辦機構

Co-organizer :



支持機構

Supporting Organizations :



香港汽車零部件工業協會
Hong Kong Auto Parts Industry Association



Hong Kong Medical and Healthcare Device Industries Association



Hong Kong Surface Finishing Society



Hong Kong Critical Components Manufacturers Association
香港關鍵性零部件製造業協會



Hong Kong Electronics Industry Council
香港電子業總會



Hong Kong Science & Technology Parks

HKPC

HKPC Building, 78 Tat Chee Avenue, Kowloon, Hong Kong T 852.2788.5678 F 852.2788.5900
香港九龍達之路78號生產力大樓 www.hkpc.org

單元三：MEMS 傳感器/器件的封裝、可靠性測試和認證

Module III: Packaging, Reliability Testing and Qualification of MEMS sensors/devices

- * 瞭解與 MEMS 傳感器/器件封裝相關的注意事項和問題
- * 主要的 MEMS 失效機理
- * 可靠性測試和壽命評估
- * 加速測試理論與技術 (與案例研究)
- * Review of packaging considerations and problems associated with MEMS
- * Identification of main MEMS failure mechanisms
- * Qualification of reliability and lifetime evaluation
- * Accelerated testing theory and technology (with case-studies)

單元四：實例分析 (微型機械傳感器、微光機電系統、生物微機電系統 - 概論及應用)

Module IV: Case Studies (Mechanical micro-sensors, MOEMS, BIOMEMS-Basics and applications)

- * 微型機械傳感器：基本的結構設計和運作原理，如壓力傳感器，加速度計等
- * 生物微機電系統：微流體技術及相關器件，如微通道，閥，泵，細胞分離系統及生物傳感器等
- * 微光機電系統：基本光學 MEMS，光學開關，微反射鏡 (DMD)，微型光電流體系統及光機傳感器。
- * 涵蓋大多數 MEMS 產品成功案例和在各行各業的潛在應用，如生物醫學、汽車及電子等。
- * Mechanical micro-sensors: basic microstructures and design & working mechanisms, pressure sensors, accelerometer
- * BioMEMS: basic of microfluidics, channels, valves, pumps, cell separation system and biosensors
- * MOEMS: basic of optical MEMS, optical switch, micro-mirrors (DMD), micro-opto fluidic system and optoelectronic sensors
- * These topics cover most of the successful and upcoming products of MEMS and the emerging applications of MEMS sensors for electronic, automotive and biomedical applications

單元五：實踐課 (微機電系統 MEMS 製程) Module V: Practical sessions on MEMS processes

- * 鞏固單元二的理論
- * 體驗在潔淨室進行基本 MEMS 製程 (體細微加工和表面微加工工藝): 光刻, 乾法刻蝕, 薄膜沉積和晶圓鍵合。
- * The practical sessions would enhance the theory covered in training module II
- * Participants would acquire hands-on experience in bulk micromachining and surface micromachining processes for MEMS fabrication in the cleanroom. Some processes covered are photolithography, dry etching, thin film deposition and wafer bonding

前往當地著名企業及研究所瞭解當地產業如何應用 MEMS 傳感器的個案分享

Visit to MEMS foundries or research institutes

A*STAR SIMTech Microfluidics Foundry, Singapore Institute of Manufacturing Technology
新加坡科技研究局製造技術研究所 微流體代工廠 (<http://smf.simtech.a-star.edu.sg/>)

A*STAR SIMTech Precision Engineering Centre of Innovation (Meeting with Surface Technology Group)
新加坡科技研究局製造技術研究所 創新精密工程中心(跟表面技術專家會面)
(<http://www.simtech.a-star.edu.sg/PECOI>)

A*STAR Institute of Microelectronics, Singapore (IME) (To be confirmed)
新加坡國家科技局微電子研究所 (待定) (<http://www.ime.a-star.edu.sg/>)

Memstech Corp. (To be confirmed) 微型傳感器/麥克風工廠 (待定) (<http://www.memstech.com/>)

培訓師資 Trainers Profile

Dr. Holden Li, Assistant Professor of Nanyang Technological University (新加坡南洋理工大學助理教授)

- * PhD in Mechanical Engineering, Stanford University
- * Lead a research team in MEMS sensors research effort in the area of MEMS R&D and reliability study
- * Work closely with several senior faculties in the area of microelectronics and MEMS research both in NTU and Temasek Laboratories at NTU.
- * 美國史丹福大學 (Stanford University) 機械工程博士
- * 帶領 MEMS 傳感器的研究小組致力研發 MEMS 及其可靠性研究
- * 目前正與幾位在新加坡南洋理工大學及 Temasek Laboratories 的資深教授緊密合作，進行有關微電子和 MEMS 的研究。

主辦機構
Organizer :



協辦機構
Co-organizer :



支持機構
Supporting Organizations :



製造科技 MANUFACTURING TECHNOLOGY

Dr Ng Sum Huan Gary, Research Scientist at the A*STAR Singapore Institute of Manufacturing Technology (新加坡科技研究局製造技術研究所研究科學家)

- * Ph.D. from the George W. Woodruff School of Mechanical Engineering at Georgia Institute of Technology (U.S.A.)
- * Bachelor and Master degrees in Mechanical Engineering from the National University of Singapore
- * His research interests are microfluidics, microfabrication techniques and abrasive removal processes.
- * Secured research grants as a co-principal investigator in the area of microfluidics and Bio MEMS
- * Authored/co-authored over 40 journal/conference publications/books and filed various patents in manufacturing processes and microfluidics
- * 美國佐治亞理工學院 (Georgia Institute of Technology) 博士
- * 新加坡國立大學 National University of Singapore (機械) 工程學士及碩士
- * 研究方向是微流體、微製造技術和研磨去除過程。
- * 曾參與有關微流體和生物微機電系統的資助研究項目。
- * 撰寫/共同撰寫超過 40 編有關製造工藝和微流體領域的期刊/會議論文/書籍及申請多項專利。

Cassandra Low Lee Ngo, Senior Lecturer at Singapore Polytechnic (新加坡理工學院電氣與電子工程高級講師)

- * Graduated from National University of Singapore with a Bachelor of Engineering (Honors) and MSC
- * Involved in setting up the IC Design and Nanofabrication centre for wafer and MEMS fabrication in 2000
- * 新加坡國立大學工程學 (榮譽) 學士及理學碩士
- * 於 2000 年參與設立集成電路設計與納米製造中心，主要供晶圓和 MEMS 製造。

Ho Soon Seng, Senior Lecturer at Singapore Polytechnic (新加坡理工學院高級講師)

- * Graduated from University of Kansas, USA with BSEE in 1978 and MSEE in 1982
- * Joined Singapore Polytechnic in 2003 and has been involved in the manpower training for the wafer specialist program in 1990s
- * Involved in several funded MEMS projects since 2002 such as pressure sensor, MEMS based devices for data storage applications (collaboration with ASTAR research institution), biochip (industry), etc
- * 美國堪薩斯大學電子工程學士及碩士
- * 2003 年加入新加坡理工學院，並參與晶圓專家計劃 (wafer specialist program) 的人力培訓。
- * 自 2002 年以來參與了多個有關微機電系統的資助項目，如壓力傳感器、微機電系統的數據存儲應用 (與 A*STAR 研究所合作)、生物芯片 (與工業界合作) 等。

詳情 Details

費用: 每位港幣 19,100 元正(支持機構會員每位港幣 18,145 元)

Fee for each participant : HK\$19,100 (Member of supporting organizations: HK\$18,145)

(成功申請 NTTS 之學員必須為香港永久居民，每位最高可獲港幣 6,375 元的費用資助，以上或任何培訓資助申請及審批成功與否由本地有關機構審批決定。如參加者因任何原因而不獲資助，本局概不負責。計劃的詳細內容，請參閱 <http://ntts.vtc.edu.hk>。)

Any permanent resident in Hong Kong who is sponsored by his employer and has the necessary background/experience to benefit from the training will be eligible. The approved training grant for each eligible trainee is 50% of the actual course fee up to HK\$6,375. The application result is subject to the final decision of the funding agency. Please refer to <http://ntts.vtc.edu.hk> for the detailed application guideline.

費用包括：香港往返新加坡經濟客位機票連機場稅及燃料附加費、四晚雙人房酒店住宿連早餐 (單人房須額外收費)、三天培訓之午餐及茶點、培訓教材及其他培訓雜費、行程內交通費用、基本意外保險【只適用於香港居民及隨團往返之參加者】。

The training fee is inclusive of round-trip economy class air tickets between Hong Kong and Singapore (including airport tax, fuel and security charges), hotel for 4 nights (twin-room) with breakfast, training materials, local transportation in the itinerary, travel insurance (applied only to Hong Kong Residents and those depart and return as planned)

不包括：午餐、晚餐 (指定午餐除外)、簽證費用、行程外之額外交通費用

The training fee is NOT inclusive of meals, visa, inland transportation that is not listed in the itinerary.

此海外培訓班之機票、交通、住宿及其他旅遊事宜將由持牌旅行社負責。

Air tickets, transportation, accommodation and other arrangements will be in charge by a licensed travel agency.

主辦機構
Organizer :



協辦機構

Co-organizer :



支持機構

Supporting Organizations :



HKPC®

HKPC Building, 78 Tat Chee Avenue, Kowloon, Hong Kong T 852.2788.5678 F 852.2788.5900
香港九龍達之路78號生產力大樓 www.hkpc.org

General Terms and Conditions

This study mission ("Mission") is subject to the following terms and conditions:

1. Acceptance

HKPC may in its absolute discretion accept or reject the Application without providing any reasons therefor.

2. Payment

- a) Upon submission of Application, the Applicant shall pay to HKPC the Participation Fee.
- b) If the Application is rejected, HKPC will refund to the Applicant without interest.
- c) When the Application is accepted by HKPC, the Applicant will become a Participant. If the Participant subsequently wishes to withdraw participation, he/she may do so by notice in writing to HKPC prior to the departure date of the Mission according to the number of days prescribed in the pamphlet for the Mission whereupon the Participation Fee may be refunded subject to the deduction of any costs already paid by HKPC which are otherwise unrecoverable through HKPC's service providers. An administration fee as prescribed in the pamphlet for the Mission will be charged to the Participant.
- d) The Participant shall settle the hotel directly all additional charges incurred by them at the hotel when they check out from the hotel.
- e) No interest will be payable by HKPC in respect of any refund amounts to the Participant.

3. Termination Policy

- a) Without prejudice to HKPC's other rights and remedies, HKPC has the right to terminate the Participant's right to participate in the Mission on the occurrence that the Participant violates any of the terms or requirements contained in these Conditions.
- b) The Participant's right to participate in the Mission shall automatically terminate in the event that all or most of the Participants are refused entry visa or entry permit to the country or place where the Mission shall be held by any competent authorities.
- c) In the event that the Participant's right to participate in the Mission is terminated, the Participation Fee will not be refunded to the Participant and any expenses incurred by HKPC for an on behalf of the Participant prior to such termination and all other expenses reasonably incurred by HKPC as a consequence of such termination shall be paid on demand by the Participant to HKPC.
- d) HKPC reserves the right to terminate the Participant's right to participate or continue to participate in any future Mission if the Participant is found to have committed any act including but not limited to failing to respect the intellectual property rights of any other party, non-compliance with product safety, environmental laws and/ or any other act which, in the sole opinion of HKPC, might damage the reputation and/ or image of Hong Kong, the industries, the Mission, HKPC, or the Participant has done or failed to do any act which HKPC, in its absolute discretion decides that such right shall be terminated.

4. Cancellation and/ or Changes

- a) HKPC reserves the right in any circumstances to cancel the Mission, for example because of an insufficient number of Participants or for whatever reason. If HKPC cancels the Mission, then save for an event set out in clause 4(e) below, HKPC's liability shall be limited to the amount of the fee actually paid by the Participant for that Mission.
- b) The dates and itinerary of the Mission may be subject to change without prior notice. HKPC reserves the right to use alternative accommodation, tours and transport to those stated in the Mission's promotional leaflets.
- c) Fees may be subject to changes, including without limitation surcharges, airfare, fuel or tax increases and currency fluctuations. HKPC reserves the right to charge Participants for all additional costs arising from such changes.
- d) Fees paid are not refundable on any unused part of the Mission or in the event that a Participant cancels participation in the Mission for any reason. Prior to the commencement of a Mission, HKPC may at its sole discretion accept a substitute nominated by the Participant to attend the Mission on his or her behalf, or accept request for change in departure/ return dates or transport arrangements, subject to the payment of any additional fees and charges that may be incurred by HKPC in agreeing to such a substitute or change.
- e) HKPC shall not be liable to any Participant for any delay, non-performance of services, loss or damage arising from any cause or causes beyond its reasonable control including, without limitation, any of the following: act of God, governmental act, war, terrorist attacks, fire, flood, earthquake, storm, tsunami, embargo, explosion or civil commotion. In such an event, HKPC reserves the right, at its sole discretion, to:
 - (i) postpone the Mission and/ or alter the dates and itinerary of the Mission as necessary without any refund due to the Participant; or
 - (ii) cancel the Mission and offer Participants a refund subject to the deduction of any costs already paid by HKPC which are otherwise unrecoverable through HKPC's service providers.

5. Exclusion of Liability

- a) HKPC shall not be liable for any loss, damage or personal injury howsoever suffered by or caused to the Participant or his/her officers, representatives, agents, employees or any third party, or other property in the course or in relation to the Mission, unless such loss, damage or personal injury shall be caused by any breach by HKPC.
- b) HKPC assumes no responsibilities for any introduction or transaction made between the Participant and any third party during or as a result of the Mission.
- c) The Participant shall be responsible for his/her own visa arrangements. In the event that a Participant is refused entry into any country on a Mission, HKPC shall not be liable for any loss of damage suffered.
- d) The Participant shall be responsible for effectuating all insurance coverage necessary in connection with his/her participation in the Mission including but not limited to insurance in respect of his/her other property and himself/herself (including travel and medical insurance).
- e) The Participant undertakes to indemnify and at all times hereafter to keep indemnified HKPC from an against all liabilities, actions, proceedings, claims, damages, costs and expenses whatsoever which he/she may suffer or incur by reason of or in relation to any act, omission or default by the Participant or his/her officers, representatives, agents and employees in the course of or in relation to the Mission.

6. General

- a) The Application Form and the Conditions embody and set out the entire agreement and understanding of the parties and supersede all prior oral or written agreements, understandings or arrangements between HKPC and the Applicant relating to the Mission.
- b) HKPC reserves the right to alter and amend any of these Conditions and to issue additional rules and regulations (including but not limited to the Participant's manual) at any time it considers necessary for the orderly operation of the Mission. The amended Conditions and the additional rules and regulations shall be sent to the Participant and become effective immediately. The Participant will be deemed to have notice of the same and have accepted the amended Conditions and the additional rules and regulations. The Participant acknowledges that HKPC shall have the right to interpret these Conditions, additional rules and regulations together any amendments thereof. All interpretations of these Conditions, any additional rules and regulations, and any amendments thereof by HKPC shall be final and binding on the Participants.
- c) These Conditions shall be governed by the laws of The Hong Kong Special Administrative Region only.

Enrollment Form

報名表

For enrollment, please send the completed enrollment form to maylau@hkpc.org on or before 30th January, 2015 for reservation. Successful applicants will be notified by email.

Quota : 20.

Please complete this form in BLOCK LETTERS

Enquiry:

Ms May Lau

Tel: (+852) 2788 6324

 Email: maylau@hkpc.org

Dr. Carmen Fung

Tel: (+852) 2788 6129

 Email: carmenfung@hkpc.org

Overseas Training Course to Singapore on Advanced Micro-Sensor
and Components Manufacturing and Application Technologies
23 – 27 March 2015

Name in English : (MUST be the same as shown in passport)		PHOTO
Name in Chinese : (Dr / Ir / Mr / Mrs / Ms *)		
Position :		
Company Name :		
Company address :		
Tel : (Office)		Tel : (Mobile)
Email address :		
Passport number :	Programme fee ** :	
Passport type** :	<input type="checkbox"/> Normal: HK\$19,100 <input type="checkbox"/> Discounted price: HK\$18,145, please specify:	
<input type="checkbox"/> HKSAR Passport <input type="checkbox"/> Others, please specify :	<input type="checkbox"/> HKETA <input type="checkbox"/> HKMHDIA <input type="checkbox"/> HKAPIA <input type="checkbox"/> HKEIC <input type="checkbox"/> HKSTP <input type="checkbox"/> HKSFS <input type="checkbox"/> HKCCMA	
Membership ID No.: _____		
Special arrangement (if any) For example, earlier flight back or stay behind / upgrading to business class / special meal arrangement (e.g. vegetarian food)		

*Delete whichever inappropriate

**Please put a "✓" in the box as appropriate

Declaration :

1. I agree that the information provided above, will be used to process my application to participate in the overseas training course, such information may be provided to the local and national agencies, institutions or other relevant organizers.
 2. I declare that all information provided in this enrolment form and the accompanying documents are, to the best of my knowledge, true, accurate and complete. **I have read and accepted** all the terms and conditions of this study mission.
- I object to the proposed use of my personal data including, without limitation, name, age, gender, phone number, fax number, job title, member status, payment details including credit card information (where applicable), academic and professional qualification, correspondence address and email address ("Personal Data") for the purpose of sending me information relating to HKPC's latest developments, industry support services, consultancy services, training courses and related events, and other marketing activities as may be organized by HKPC. Please put a "✓" in the box as appropriate.

Signature of applicant : _____

Date: _____

IMPORTANT NOTE:

1. Personal Data collected will be used for processing your application for admission, registration, academic, administrative, research and statistical purposes and will also be used for marketing purposes, specifically for the purpose of sending you information relating to HKPC's latest developments, industry support services, consultancy services, events and training courses. Personal Data will be treated in strict confidence. Unless otherwise agreed by you, Personal Data will not be transferred to any third parties. HKPC implements a policy governing the collection, use and retention of Personal Data, which is made available at the enrolment counter. You may also contact Personal Data Controlling Officer of HKPC for further details.
2. The dates and itinerary of the course may be subject to change without prior notice. HKPC reserves the right to use alternative accommodation, tours and transport to those stated in the course's promotional leaflets.
3. Applicants are encouraged to pay by cheques, if possible, amount received will be imprinted. Cheques are subject to bank clearance.
4. Enrolment fee (in full or in part) is not refundable except if HKPC is notified in writing of your withdrawal at least 30 working days before the study mission commences. A handling charge of HK\$2,000 will also be levied.
5. HKPC reserves the right to reject any application in any circumstances and for whatever reasons. Payment of fees should only be construed as conditional acceptance of application.